

STS11NF30L

N-channel 30V - 0.0085Ω - 11A SO-8 Low gate charge STripFETTM II Power MOSFET

General features

Туре	V _{DSS}	R _{DS(on)}	I _D
STS11NF30L	30V	<0.009Ω	11A

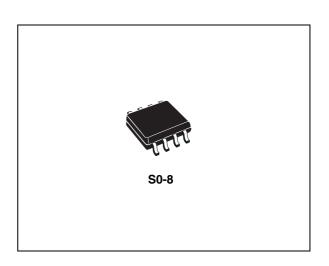
- Optimal R_{DS}(on) x Qg trade-off
- Conduction losses reduced

Description

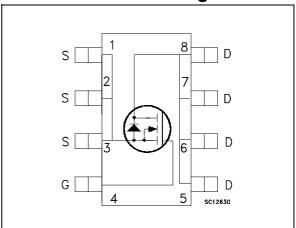
This Power MOSFET is the latest development of STMicroelectronis unique "Single Feature SizeTM" strip-based process. The resulting transistor shows extremely high packing density for low onresistance, rugged avalanche characteristics and less critical alignment steps therefore a remarkable manufacturing reproducibility.

Applications

■ Switching application



Internal schematic diagram



Order codes

Part number	Marking	Package	Packaging
STS11NF30L	11F30L-	SO-8	Tape & reel

Contents STS11NF30L

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STS11NF30L Electrical ratings

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit	
V _{DS}	Drain-source voltage (V _{GS} = 0)	30	V	
V _{GS}	Gate-source voltage	± 18	٧	
I _D ⁽¹⁾	Drain current (continuous) at T _C = 25°C	11	Α	
I _D	Drain current (continuous) at T _C = 100°C	7	Α	
I _{DM} ⁽²⁾	Drain current (pulsed)	44	Α	
P _{TOT}	Total dissipation at T _C = 25°C	2.5	W	
	Derating factor	0.02	W/°C	
dv/dt ⁽³⁾	Peak diode recovery voltage slope	5.5	V/ns	
T _J T _{stg}	Operating junction temperature Storage temperature	-55 to 150 150	l °C	

- 1. Current limited by the package
- 2. Pulse width limited by safe operating area
- 3. $I_{SD} \le 1A$, di/dt $\le 370A/\mu s$, $V_{DD} \le V_{(BR)DSS}$, $T_j \le T_{JMAX}$

Table 2. Thermal data

R _{thj-a}	Thermal resistance junction-ambient Max ⁽¹⁾	50	°C/W
T _I	Maximum lead temperature for soldering purpose	150	°C

^{1.} When Mounted on 1 inch² FR-4 board, 2 oz of Cu and t [10 sec

Electrical characteristics STS11NF30L

2 Electrical characteristics

(T_{CASE} =25°C unless otherwise specified)

Table 3. On/off states

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-source breakdown voltage	$I_D = 250 \mu A, V_{GS} = 0$	30			V
	Zero gate voltage	V _{DS} = Max rating			1	μΑ
I _{DSS}	drain current (V _{GS} = 0)	V _{DS} =Max rating, T _C =125°C			10	μΑ
I _{GSS}	Gate-body leakage current (V _{DS} = 0)	V _{GS} = ± 18V			±100	nA
V _{GS(th)}	Gate threshold voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1			٧
R _{DS(on)}	Static drain-source on resistance	$V_{GS} = 10V, I_D = 5.5A$ $V_{GS} = 5V, I_D = 5.5A$		0.0085 0.0145	0.0105 0.0190	Ω Ω

Table 4. Dynamic

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
g _{fs} ⁽¹⁾	Forward transconductance	$V_{DS} = 25V_{,} I_{D} = 5.5A$		15		S
C _{iss}	Input capacitance			1440		pF
C _{oss}	Output capacitance	$V_{DS} = 25V, f = 1 MHz,$		560		pF
C _{rss}	Reverse transfer capacitance	$V_{GS} = 0$		135		pF
Qg	Total gate charge	V 45V 1 44A		22.5	30	nC
Q_{gs}	Gate-source charge	$V_{DD} = 15V, I_D = 11A,$ $V_{GS} = 5V$		9		nC
Q_{gd}	Gate-drain charge	·GS = • •		12		nC

^{1.} Pulsed: Pulse duration = $300 \mu s$, duty cycle 1.5.

Table 5. Switching times

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t _{d(on)}	Turn-on delay time Rise time	V_{DD} =15 V, I_{D} =5.5A, R_{G} =4.7 Ω , V_{GS} =5V (see Figure 13)		22 39		ns ns
t _{d(off)}	Turn-off-delay time Fall time	V_{DD} = 15V, I_D = 5.5A, R_G = 4.7 Ω , V_{GS} = 5V (see Figure 13)		23 16		ns ns

Table 6. Source drain diode

Symbol	Parameter	Test conditions	Min	Тур.	Max	Unit
I _{SD}	Source-drain current				11	Α
I _{SDM} ⁽¹⁾	Source-drain current (pulsed)				44	Α
V _{SD} ⁽²⁾	Forward on voltage	$I_{SD} = 11A, V_{GS} = 0$			1.2	V
t _{rr} Q _{rr} I _{RRM}	Reverse recovery time Reverse recovery charge Reverse recovery current	I_{SD} = 11A, V_{DD} = 20V di/dt = 100A/ μ s, T_j = 150°C (see Figure 15)		42 52 2.5		ns nC A

^{1.} Pulse width limited by safe operating area.

^{2.} Pulsed: Pulse duration = 300 μs , duty cycle 1.5 %

Electrical characteristics STS11NF30L

2.1 Electrical characteristics (curves)

Figure 1. Safe operating area

Figure 2. Thermal impedance

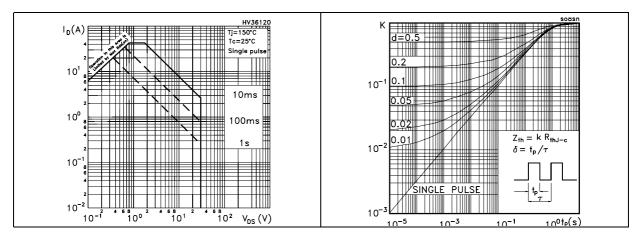


Figure 3. Output characterisics

Figure 4. Transfer characteristics

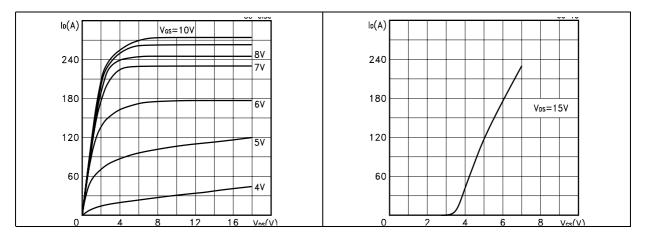
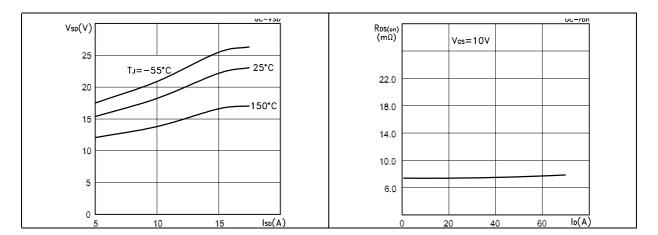


Figure 5. Transconductance

Figure 6. Static drain-source on resistance



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Figure 7. Gate charge vs gate-source voltage Figure 8. Capacitance variations

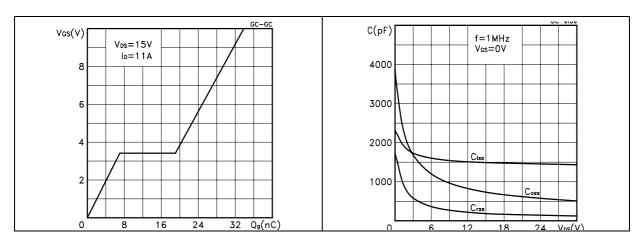


Figure 9. Normalized gate threshold voltage Figure 10. Normalized on resistance vs vs temperature temperature

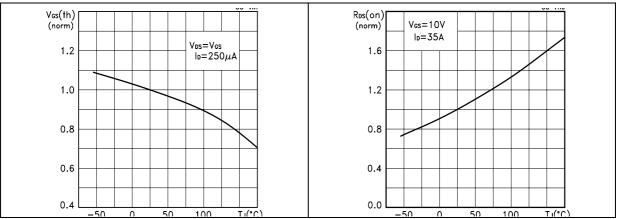
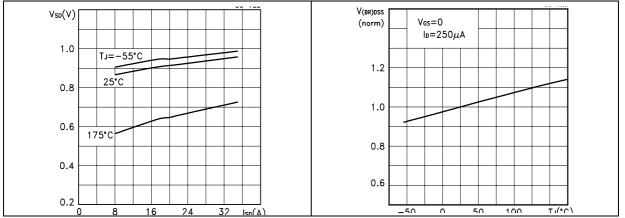


Figure 11. Source-drain diode forward characteristics

Figure 12. Normalized Breakdown Voltage vs Temperature



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Test circuit STS11NF30L

3 Test circuit

Figure 13. Switching times test circuit for resistive load

Figure 14. Gate charge test circuit

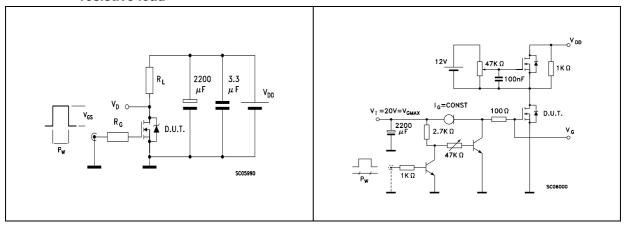


Figure 15. Test circuit for inductive load switching and diode recovery times

Figure 16. Unclamped Inductive load test circuit

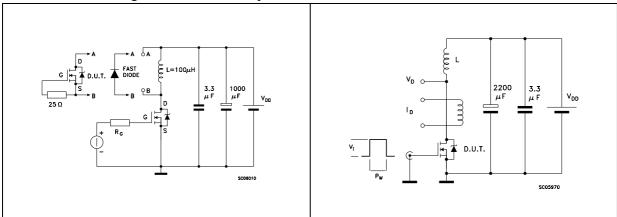
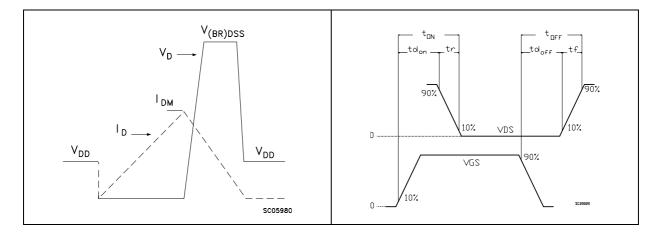


Figure 17. Unclamped inductive waveform

Figure 18. Switching time waveform

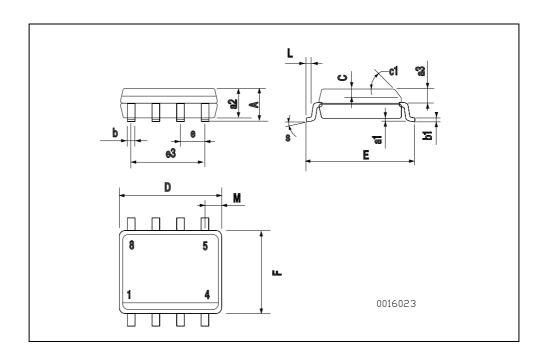


4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect . The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com

SO-8	MECH	ANICAL	DATA
-U-U		\neg	

DIM.		mm.			inch		
DIWI.	MIN.	TYP	MAX.			MAX.	
Α			1.75			0.068	
a1	0.1		0.25	0.003		0.009	
a2			1.65			0.064	
a3	0.65		0.85	0.025		0.033	
b	0.35		0.48	0.013		0.018	
b1	0.19		0.25	0.007		0.010	
С	0.25		0.5	0.010		0.019	
c1			45	(typ.)			
D	4.8		5.0	0.188		0.196	
Е	5.8		6.2	0.228		0.244	
е		1.27			0.050		
e3		3.81			0.150		
F	3.8		4.0	0.14		0.157	
L	0.4		1.27	0.015		0.050	
М			0.6			0.023	
S		8 (max.)					



STS11NF30L Revision history

5 Revision history

Table 7. Revision history

Date	Revision	Changes
09-Sep-2004	9	Complete version
17-Aug-2006	10	The document has been reformatted
12-Jan-2007	11	Updates in Safe operating area

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